

# BIPOLAR ANALOG INTEGRATED CIRCUIT

# $\mu$ PC8232T5N

## SiGe:C LOW NOISE AMPLIFIER FOR GPS

### DESCRIPTION

The  $\mu$ PC8232T5N is a silicon germanium carbon (SiGe:C) monolithic integrated circuit designed as low noise amplifier for GPS. This device exhibits low noise figure and high power gain characteristics, so this IC can improve the sensitivity of GPS receiver. In addition, the  $\mu$ PC8232T5N which is included output matching circuit contributes to reduce external components and system size.

The package is a 6-pin plastic TSON (Thin Small Out-line Non-leaded) suitable for surface mount.

This IC is manufactured using our UHS4 (Ultra High Speed Process) SiGe:C bipolar process.

### FEATURES

- Low noise : NF = 0.95 dB TYP. @  $f_{in}$  = 1 575 MHz
- High gain : GP = 17 dB TYP. @  $f_{in}$  = 1 575 MHz
- Low current consumption :  $I_{CC}$  = 3.0 mA TYP. @  $V_{CC}$  = 3.0 V
- Built-in power-saving function
- High-density surface mounting : 6-pin plastic TSON package (1.5 × 1.5 × 0.37 mm)
- Included output matching circuit
- Included very robust bandgap regulator (Small  $V_{CC}$  and  $T_A$  dependence)
- Included protection circuits for ESD

### APPLICATION

- Low noise amplifier for GPS

### ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Supplying Form
$\mu$ PC8232T5N-E2	$\mu$ PC8232T5N-E2-A	6-pin plastic TSON (Pb-Free)	6L	<ul style="list-style-type: none"> <li>• 8 mm wide embossed taping</li> <li>• Pin 1, 6 face the perforation side of the tape</li> <li>• Qty 3 kpcs/reel</li> </ul>

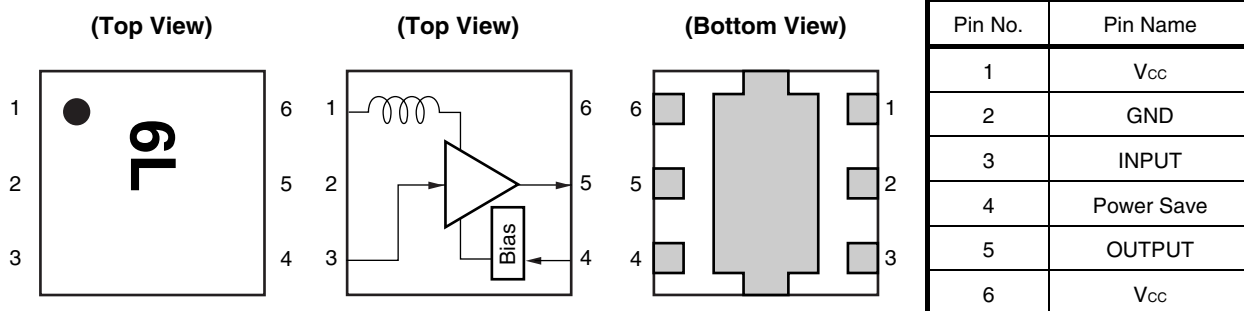
**Remark** To order evaluation samples, contact your nearby sales office.

Part number for sample order:  $\mu$ PC8232T5N

**Caution** Observe precautions when handling because these devices are sensitive to electrostatic discharge.

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# PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM



**Remark** Exposed pad : GND

## ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Test Conditions	Ratings	Unit
Supply Voltage	V <sub>CC</sub>	T <sub>A</sub> = +25°C	4.0	V
Power-Saving Voltage	V <sub>PS</sub>	T <sub>A</sub> = +25°C	4.0	V
Total Power Dissipation	P <sub>tot</sub>		150	mW
Operating Ambient Temperature	T <sub>A</sub>		−40 to +85	°C
Storage Temperature	T <sub>stg</sub>		−55 to +150	°C
Input Power	P <sub>in</sub>		+10	dBm

## RECOMMENDED OPERATING RANGE

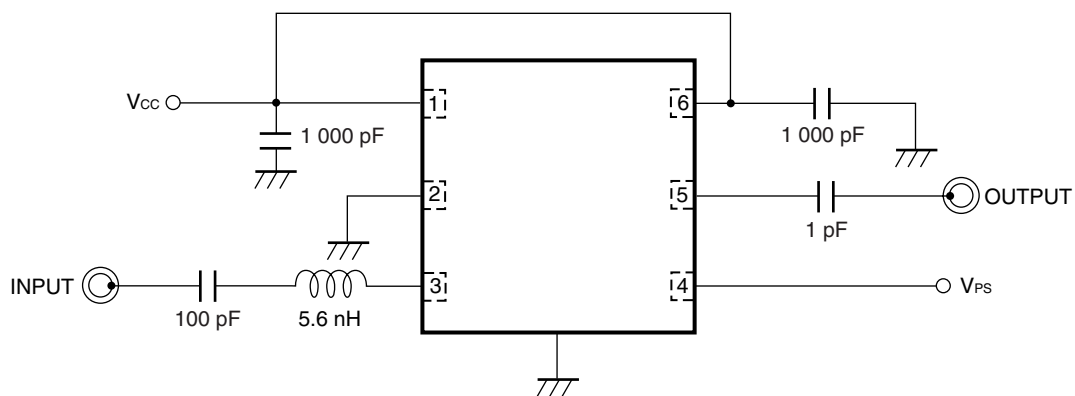
Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage	V <sub>CC</sub>	2.5	3.0	3.3	V
Operating Ambient Temperature	T <sub>A</sub>	−40	+25	+85	°C
Power Save Turn-on Voltage	V <sub>PSon</sub>	1.6	—	V <sub>CC</sub>	V
Power Save Turn-off Voltage	V <sub>PSoff</sub>	0	—	0.4	V

# ELECTRICAL CHARACTERISTICS

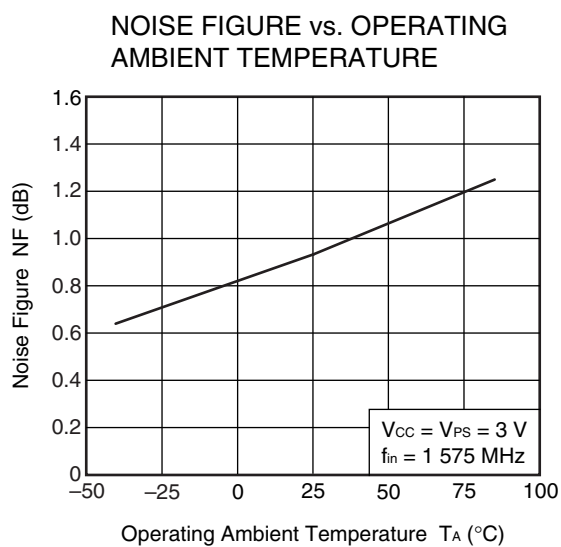
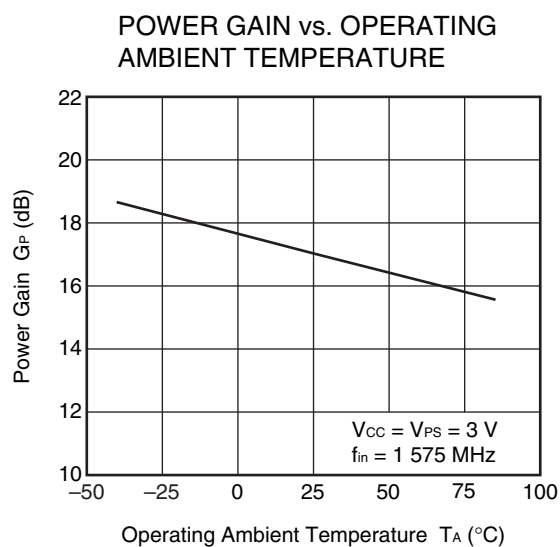
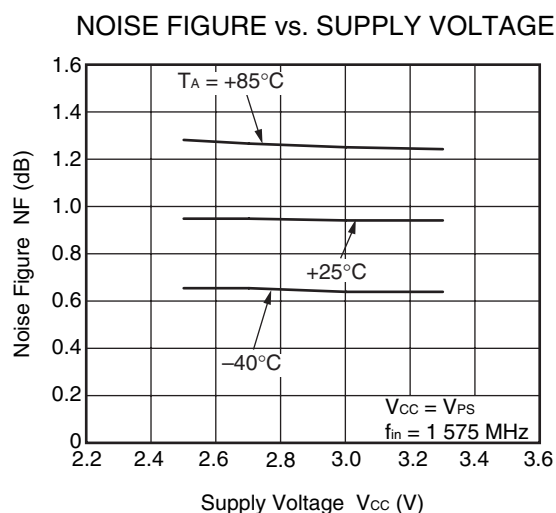
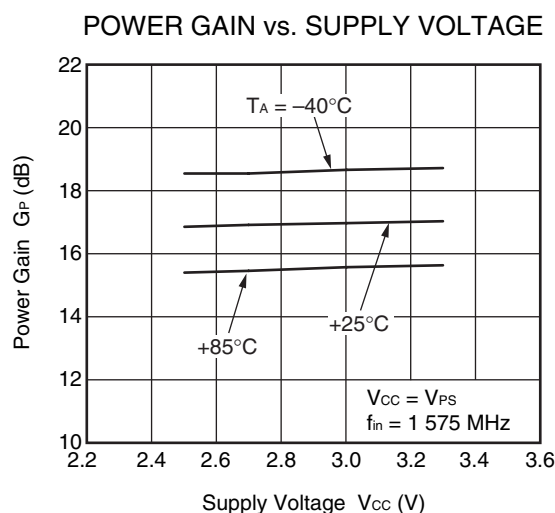
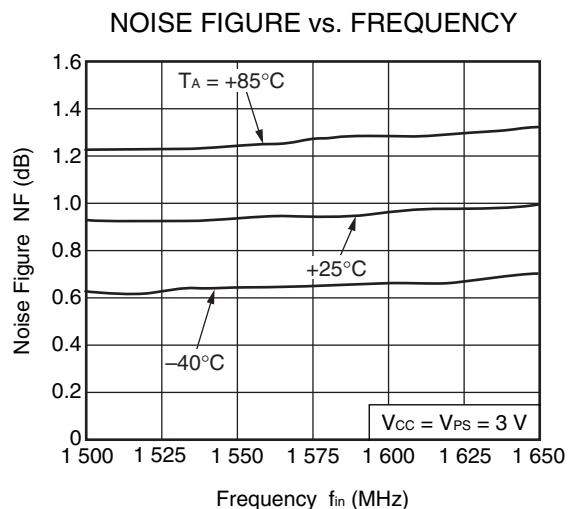
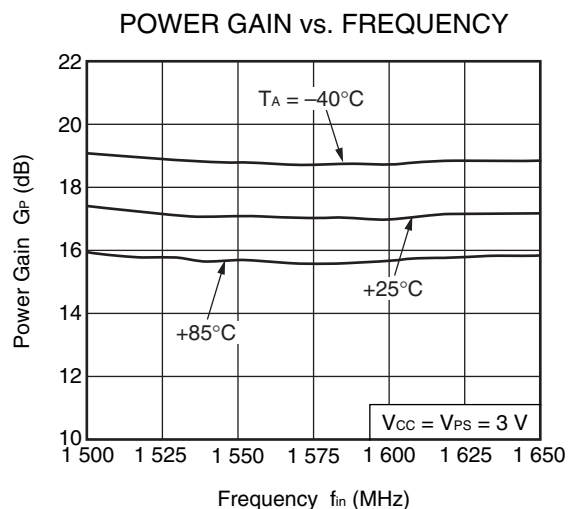
(T<sub>A</sub> = +25°C, V<sub>CC</sub> = V<sub>PS</sub> = 3.0 V, f<sub>in</sub> = 1 575 MHz, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Circuit Current	I <sub>CC</sub>	No Signal (V <sub>PS</sub> = 3.0 V)	2.3	3.0	4.1	mA
		At Power-Saving Mode (V <sub>PS</sub> = 0 V)	–	–	1	μA
Power Gain	G <sub>P</sub>	P <sub>in</sub> = –35 dBm	15	17	19	dB
Noise Figure	NF		–	0.95	1.25	dB
Input 3rd Order Intercept Point	IIP <sub>3</sub>	f <sub>in1</sub> = 1 574 MHz, f <sub>in2</sub> = 1 575 MHz	–	–8	–	dBm
Input Return Loss	RL <sub>in</sub>		7	10	–	dB
Output Return Loss	RL <sub>out</sub>		10	20	–	dB
Isolation	ISL		–	40	–	dB
Gain 1 dB Compression Input Power	P <sub>in</sub> (1 dB)		–	–21	–	dBm

## TEST CIRCUIT

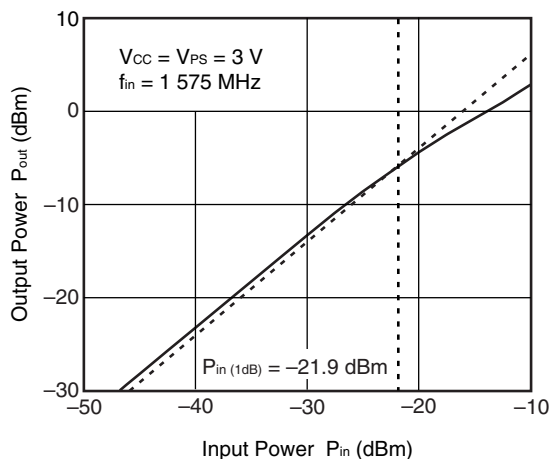


**TYPICAL CHARACTERISTICS ( $T_A = +25^\circ\text{C}$ , unless otherwise specified)**

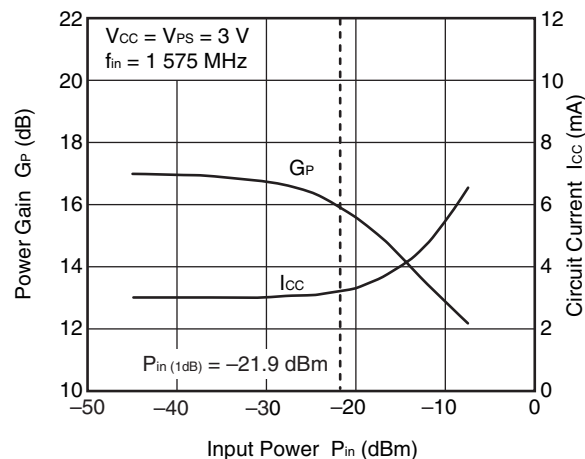


**Remark** The graphs indicate nominal characteristics.

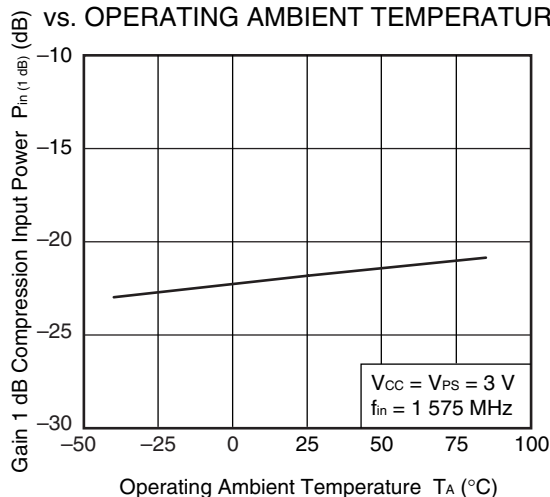
OUTPUT POWER vs. INPUT POWER



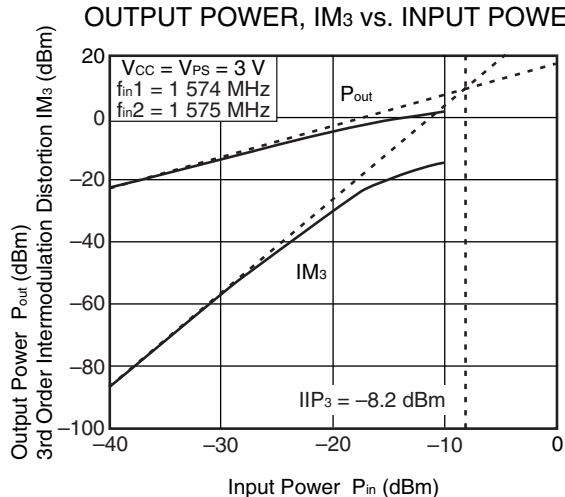
POWER GAIN, CIRCUIT CURRENT vs. INPUT POWER



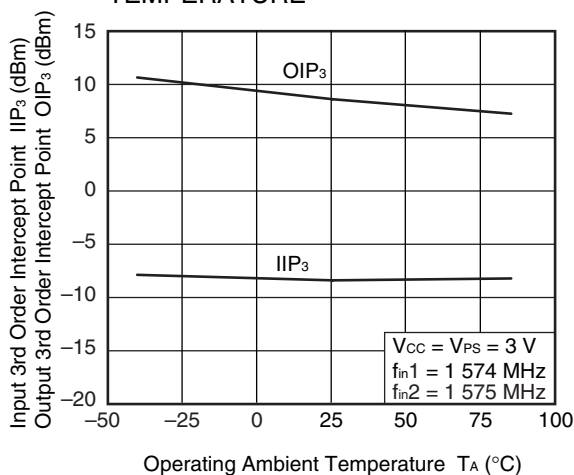
GAIN 1 dB COMPRESSION INPUT POWER vs. OPERATING AMBIENT TEMPERATURE



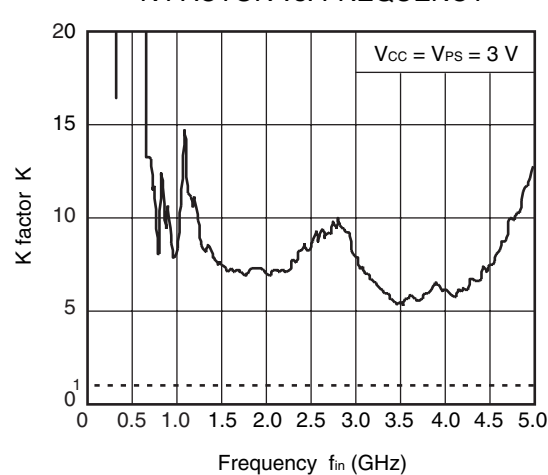
OUTPUT POWER, IM<sub>3</sub> vs. INPUT POWER



IIP<sub>3</sub>, OIP<sub>3</sub> vs. OPERATING AMBIENT TEMPERATURE

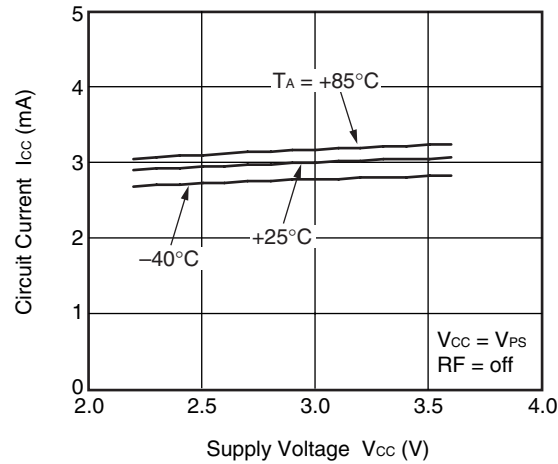


K FACTOR vs. FREQUENCY

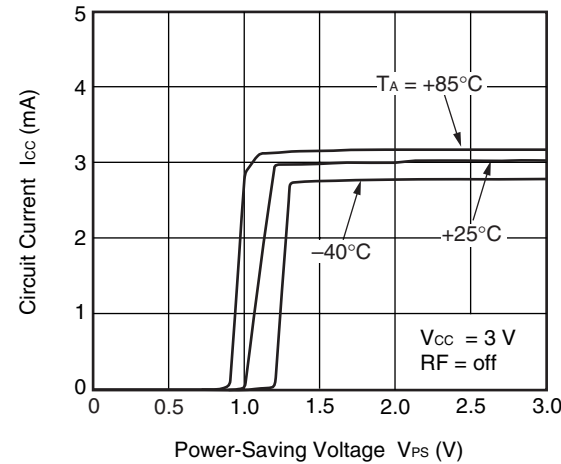


**Remark** The graphs indicate nominal characteristics.

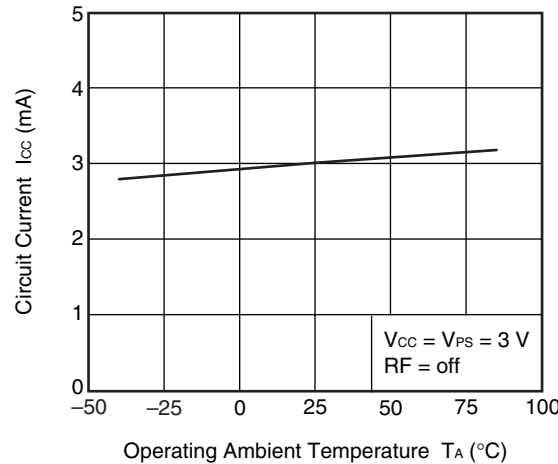
CIRCUIT CURRENT vs. SUPPLY VOLTAGE



CIRCUIT CURRENT vs. POWER-SAVING VOLTAGE



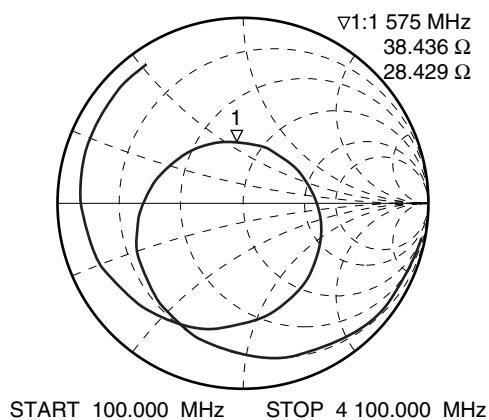
CIRCUIT CURRENT vs. OPERATING AMBIENT TEMPERATURE



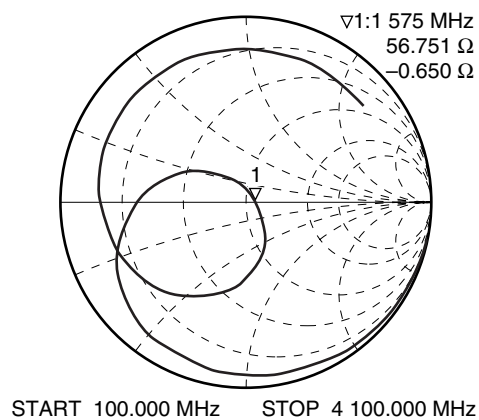
**Remark** The graphs indicate nominal characteristics.

**S-PARAMETERS** ( $T_A = +25^\circ\text{C}$ ,  $V_{CC} = V_{PS} = 3.0\text{ V}$ , monitored at connector on board)

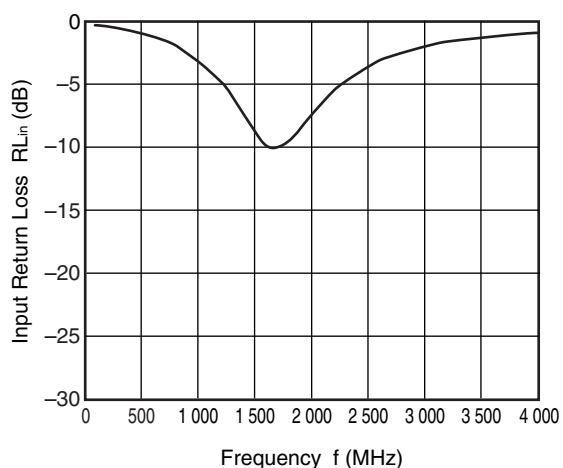
**S<sub>11</sub>—FREQUENCY**



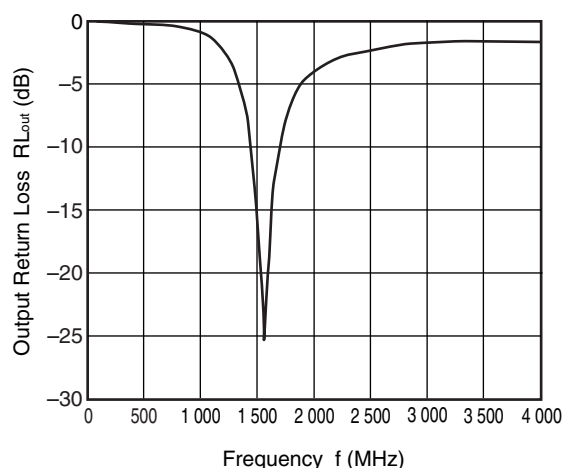
**S<sub>22</sub>—FREQUENCY**



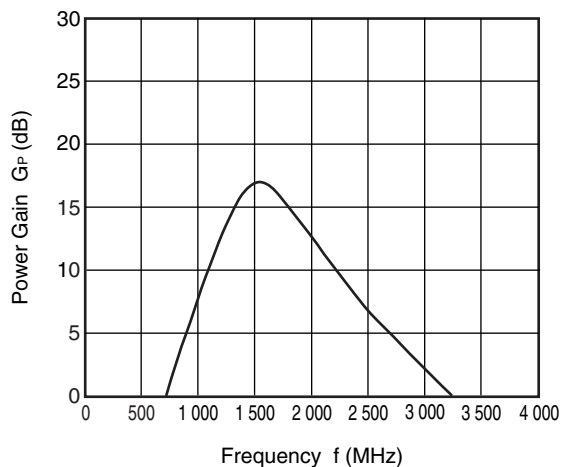
**INPUT RETURN LOSS vs. FREQUENCY**



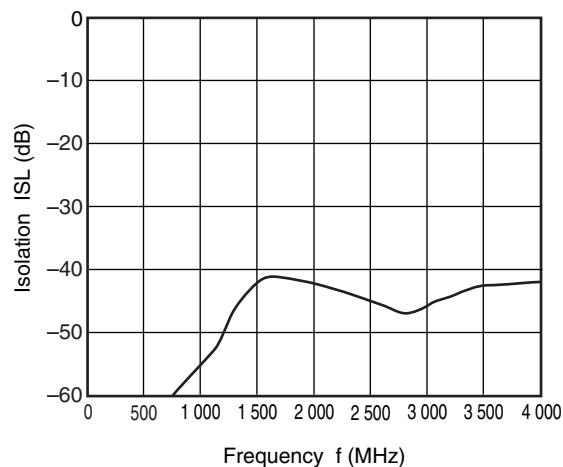
**OUTPUT RETURN LOSS vs. FREQUENCY**



**POWER GAIN vs. FREQUENCY**



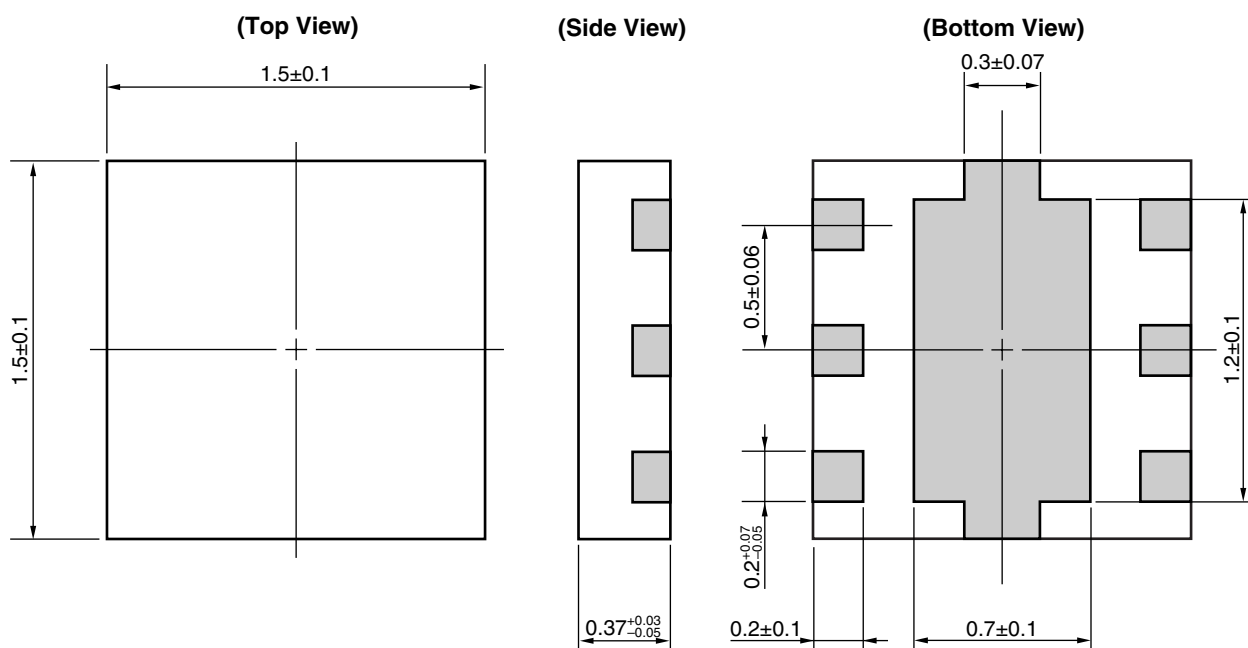
**ISOLATION vs. FREQUENCY**



**Remark** The graphs indicate nominal characteristics.

<R> PACKAGE DIMENSIONS

6-PIN PLASTIC TSON (UNIT: mm)



## NOTES ON CORRECT USE

- (1) Observe precautions for handling because of electro-static sensitive devices.
- (2) Form a ground pattern as widely as possible to minimize ground impedance (to prevent undesired oscillation).  
All the ground terminals must be connected together with wide ground pattern to decrease impedance difference.
- (3) The bypass capacitor should be attached to Vcc line.
- (4) Do not supply DC voltage to INPUT pin.

## RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions	Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) : 260°C or below Time at peak temperature : 10 seconds or less Time at temperature of 220°C or higher : 60 seconds or less Preheating time at 120 to 180°C : 120±30 seconds Maximum number of reflow processes : 3 times Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	IR260
Wave Soldering	Peak temperature (molten solder temperature) : 260°C or below Time at peak temperature : 10 seconds or less Preheating temperature (package surface temperature) : 120°C or below Maximum number of flow processes : 1 time Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (terminal temperature) : 350°C or below Soldering time (per side of device) : 3 seconds or less Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	HS350

**Caution** Do not use different soldering methods together (except for partial heating).

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